02-27-04

CEDA 7000.5 PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of Brian Lewis
Serial No. 10/722,288
Filed November 25, 2003
For THERMAL INTERFACE MATERIAL AND SOLDER PREFORMS

February 26, 2004

COMMISSIONER FOR PATENTS P.O. BOX 1450 ALEXANDRIA, VIRGINIA 22313-1450

SIR:

INFORMATION DISCLOSURE STATEMENT

In accordance with 37 C.F.R. 1.97 and 1.98 and MPEP 609, and in compliance with the duty of disclosure set forth in 37 C.F.R. 1.56, applicant submits the attached PTO/SB/08A for consideration by the Patent and Trademark Office in the above-entitled application and to be made of record therein.

Applicant is not submitting copies of any of the documents listed on the attached form because such copies were provided in 10/151,741, now 6,653,741, relied on for priority, and because such copies are excused by Rule 1.98(d). But if the examiner requires any copies, please call the undersigned and he will fax or mail them as requested.

Respectfully submitted,

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PIF/sat/leb

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^{*}EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

¹Unique citation designation number. ²See attached Kinds of U.S. Patent Documents. ³Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). ⁴For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. ⁴Applicant is to place a check mark here if English language Translation is attached or place an "A" here if English language abstract is attached..

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